



SF2235G

- 1542.5 MHz **SAW Filter**
- SM2520-5

- Low-loss SAW Filter
- 2.5 x 2.0 x 1.0 mm Surface-mount Case
- · No Matching Circuit Required

## **Absolute Maximum Ratings**

Rating	Value	Units	
Maximum Input Power	+5	dBm	
Maximum DC Voltage on any Non-ground Terminal	5	VDC	
Storage Temperature Range in Tape and Reel	-40 to +85	°C	
Maximum Soldering Profile, 5 cycles maximum	265 °C for 10 s		

#### **Electrical Characteristics**

Characteristic	Sym	Notes	Min	Тур	Max	Units
Nominal Operating Frequency	f <sub>C</sub>			1542.5		MHz
Passband Insertion Loss, 1525 to 1560 MHz	IL			2.1	3.5	dB
Amplitude Ripple, 1525 to 1560 MHz				0.9	2.0	dB <sub>P-P</sub>
Attenuation Referenced to 0 dB:						
DC to 1480 MHz			21	41		
1630 to 1660 MHz			26	34		dB
1660 to 2050 MHz			30	35		
2050 to 3500 MHz			25	50		
Source impedance, Single-ended	Z <sub>S</sub>			50 Ω	•	
Load impedance, Balanced	Z <sub>L</sub>		150 Ω    33 nH			
Operating Temperature Range	T <sub>A</sub>		-10		+75	°C

Case Style	SM2520-4		
Lid Symbolization (3G = Filter ID, Y = year, W = week)	3G, YW		

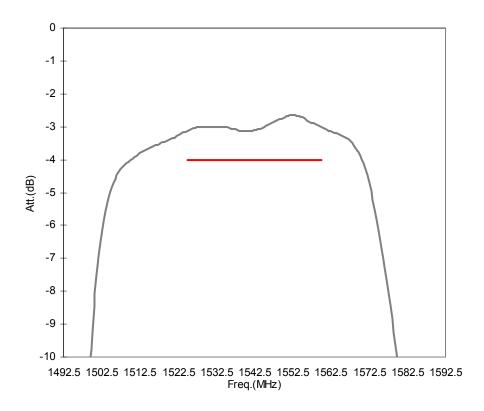
## **Electrical Connections**

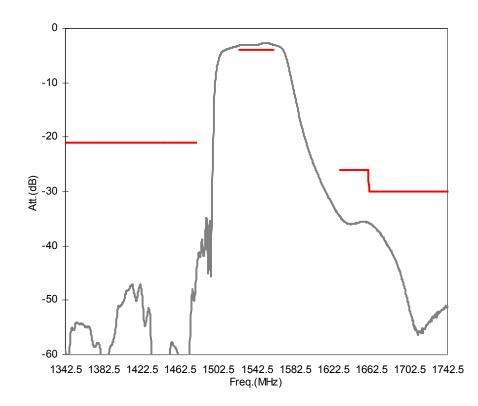
Connection	Terminals		
Input, Single-ended	1		
Output, Balanced	3, 4		
Ground	All others		

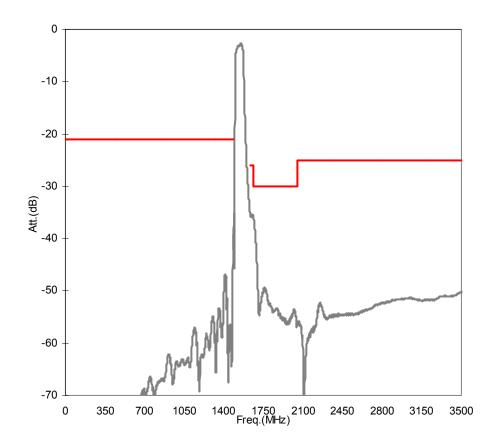
## CAUTION: Electrostatic Sensitive Device. Observe precautions for handling. NOTES:

- US and international patents may apply. Murata, stylized Murata logo, and Murata N.A., Inc. are registered trademarks of Murata Manufacturing Co., Ltd.

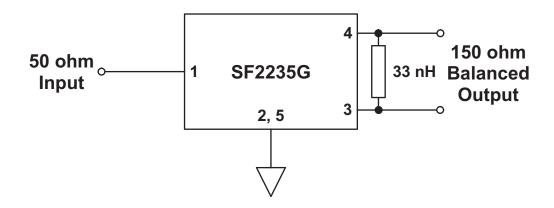
# Filter Amplitude Plots





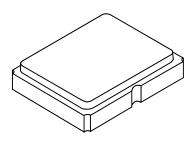


# **Filter Tuning Network**

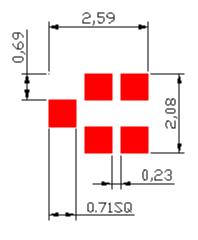


# **SM2520-5 Case**

## 5-Terminal Ceramic Surface-Mount Case 2.5 X 2.0 mm Nominal Footprint



## **PCB Footprint**



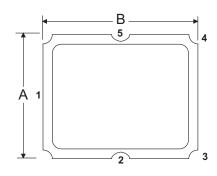
## **Case Dimensions**

Dimension	mm		Inches			
Dillichsion	Min	Nom	Max	Min	Nom	Max
Α	1.88	2.00	2.12	0.074	0.079	0.083
В	2.38	2.50	2.62	0.094	0.098	0.103
С	0.92	1.00	1.08	0.036	0.039	0.043
D		0.55			0.022	
E		0.55			0.022	
F		1.40			0.055	
G		0.50			0.020	
Н		0.08			0.003	
I		0.90			0.035	

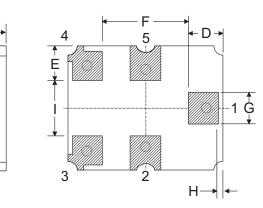
#### **Case Material**

Materials			
Solder Pad Plating	0.3 to 1.0 µm Gold over 1.27 to 8.89 µm Nickel		
Lid Plating	2.0 to 3.0 µm Nickel		
Body	Al <sub>2</sub> O <sub>3</sub> Ceramic		
	Pb Free		

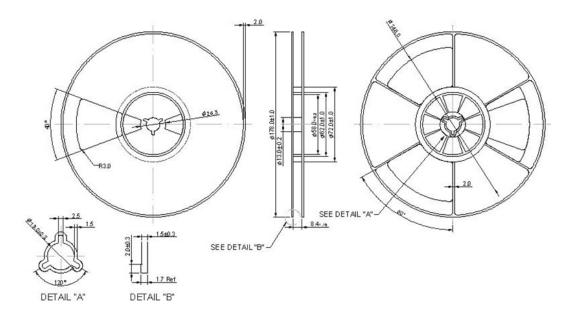
**TOP VIEW** 



# BOTTOM VIEW



## **Reel Dimension**



## **Tape Dimension**

